

# METHOD OF DEFECT CONTROL

## Abstract

A method of defect control by daily checking. First, a patterned wafer with a plurality of first defects is provided. After performing a semiconductor process, which generates a plurality of second defects on the wafer, a defect detecting process is performed to detect the first defects and the second defects. Then, the first defects and the second defects are divided according to a predetermined database. The second defects are classified into a plurality of defect types according to the predetermined database.